

ICP-COAプロセス

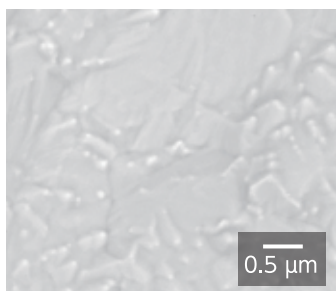
ICP-COA PROCESS

- 還元型の触媒で、銅腐食がなくボイドが発生しない
Cobalt-reduced catalyzing agent to prevent copper damage and void occurrence
- 無電解ニッケルめっき初期の被覆性に優れる
Improve electroless nickel plating deposition in initial reaction
- ファインパターン性に優れる
Excellent in fine pattern ability

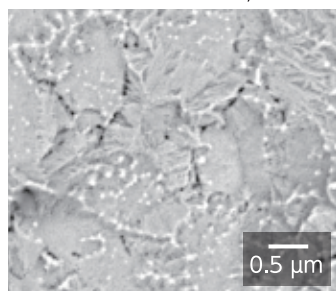
触媒付与時に銅素材を侵さず、ボイドが発生しない

Prevent copper damage and void occurrence at catalyzing step

ICP-COAプロセス
ICP-COA PROCESS

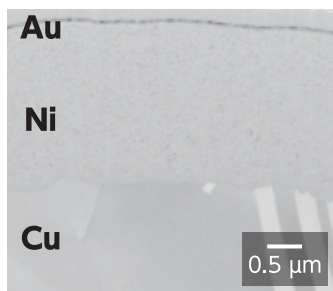


従来パラジウム触媒
Conventional Pd catalyst

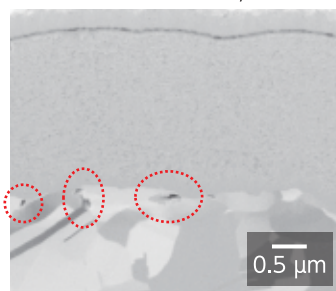


触媒付与後の表面SEM像
SEM image of surface (after catalyzing)

ICP-COAプロセス
ICP-COA PROCESS



従来パラジウム触媒
Conventional Pd catalyst

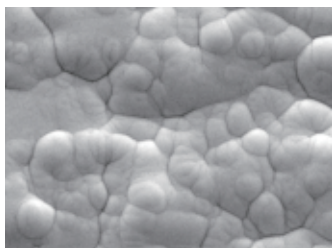


無電解ニッケル / 金めっき後の断面SIM像
SIM image of cross section (after electroless nickel/gold plating)

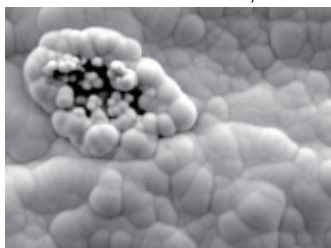
めっき初期の被覆性に優れる

Great covering power at initial plating

ICP-COAプロセス
ICP-COA PROCESS



従来パラジウム触媒
Conventional Pd catalyst



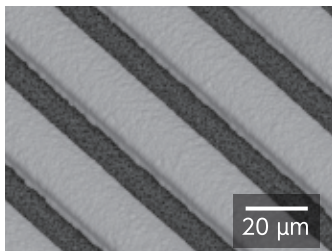
無電解ニッケルめっき後の表面SEM像
SEM image of surface (after electroless nickel plating)

ニッケル膜厚: 0.5 μm
Nickel thickness

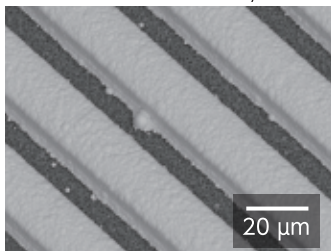
優れたファインパターン性

Excellent in fine pattern ability

ICP-COAプロセス
ICP-COA PROCESS



従来パラジウム触媒
Conventional Pd catalyst



L/S = 20 / 20 μm

無電解ニッケル / 金めっき後の表面SEM像
SEM image of surface (after electroless nickel/gold plating)

処理工程

Process

前処理

Pre-treatment

(脱脂・エッチング・酸洗)
Cleaning Etching Acid cleaning

還元型コバルト触媒

Cobalt-reduced catalysts
ICP アクセラCOA
ICP ACCERA COA

無電解ニッケルめっき

Electroless nickel plating

ICPニコロンCOA-GM (リジッド基板用)
ICP NICORON COA-GM (For Rigid)
ICPニコロンCOA-FP (フレキシブル基板用)
ICP NICORON COA-FP (For FPC)

置換金めっき

Immersion gold plating
フラッシュゴールド330S
FLASH GOLD 330S